

**Product Description**

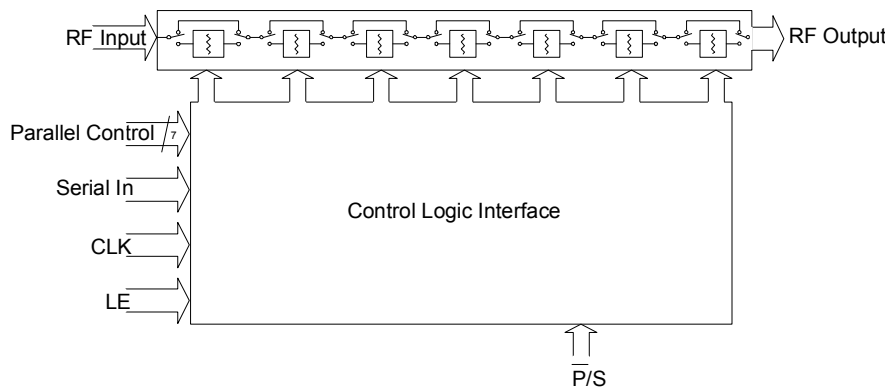
The PE43602 is a HaRP™-enhanced, high linearity, 6-bit RF Digital Step Attenuator (DSA) covering a 31.5 dB attenuation range in 0.5 dB steps. This Peregrine 50Ω RF DSA provides both a serial and parallel CMOS control interface. It maintains high attenuation accuracy over frequency and temperature and exhibits very low insertion loss and low power consumption. Performance does not change with Vdd due to on-board regulator. This next generation Peregrine DSA is available in a 4x4 mm 24 lead QFN footprint.

The PE43602 is manufactured on Peregrine's UltraCMOS™ process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

**Figure 1. Package Photo**  
24-lead 4x4x0.85 mm QFN Package



**Figure 2. Functional Schematic Diagram**



**50 Ω RF Digital Attenuator**  
**6-bit, 31.5 dB, DC-5.0 GHz**

**Features**

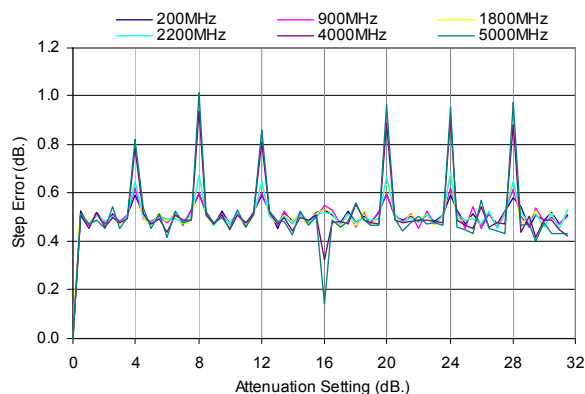
- HaRP™-enhanced UltraCMOS™ device
- Attenuation: 0.5 dB steps to 31.5-dB
- High Linearity: Typical +58 dBm IP3
  - Excellent low-frequency performance
- 3.3 V or 5.0 V Power Supply Voltage
- Fast switch settling time
- Programming Modes:
  - Direct Parallel
  - Latched Parallel
  - Serial
- High-attenuation state @ power-up (PUP)
- CMOS Compatible
- No DC blocking capacitors required
- Packaged in a 24-lead 4x4x0.85 mm QFN

**Table 1. Electrical Specifications @ +25°C, V<sub>DD</sub> = 3.3 V or 5.0 V**

| Parameter              | Test Conditions   | Frequency      | Min | Typical  | Max         | Units |
|------------------------|---|----------------|-----|----------|-------------|-------|
| Frequency Range        |   |                |     | DC – 5   |             | GHz   |
| Attenuation Range      | 0.5 dB Step   |                |     | 0 – 31.5 |             | dB    |
| Insertion Loss         |   | DC ≤ 5 GHz     |     | 2.2      | 2.7         | dB    |
| Attenuation Error      | 0 dB - 31.5 dB Attenuation settings                                       | DC < 4 GHz     |     |          | ±(0.3 + 3)% | dB    |
|                        | 0 dB - 31.5 dB Attenuation settings                                       | 4 GHz ≤ 5 GHz  |     |          | +0.4 + 5%   | dB    |
|                        | 0 dB - 31.5 dB Attenuation settings                                       | 4 GHz ≤ 5 GHz  |     |          | -0.3 - 3%   | dB    |
| Return Loss            |   | DC - 5 GHz     |     | 18       |             | dB    |
| Relative Phase         | All States  | DC - 5 GHz     |     | 55       |             | deg   |
| P1dB                   | Input   | 20 MHz - 5 GHz | 30  | 32       |             | dBm   |
| IIP3                   | Two tones at +18 dBm, 20 MHz spacing                                      | 20 MHz - 5 GHz |     | 58       |             | dBm   |
| Typical Spurious Value |   | 1 MHz          |     | -110     |             | dBm   |
| Video Feed Through     |   |                |     | 10       |             | mVpp  |
| Switching Time         | 50% DC CTRL to 10% / 90% RF   |                |     | 650      |             | ns    |
| RF Trise/Tfall         | 10% / 90% RF  |                |     | 400      |             | ns    |
| Settling Time          | RF settled to within 0.05 dB of final value<br>RBW = 5 MHz, Averaging ON. |                |     | 4        |             | µs    |

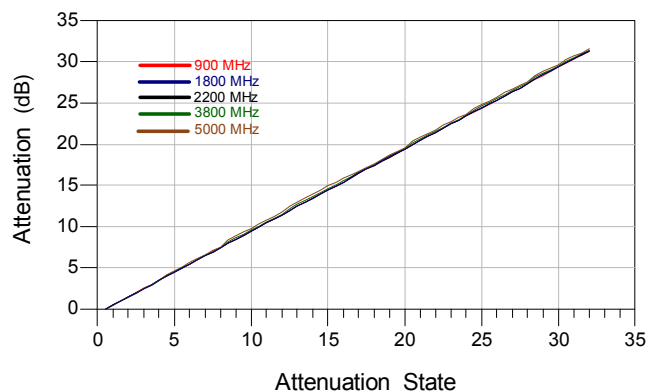
**Performance Plots**

**Figure 3. 0.5dB Step Error vs. Frequency\***

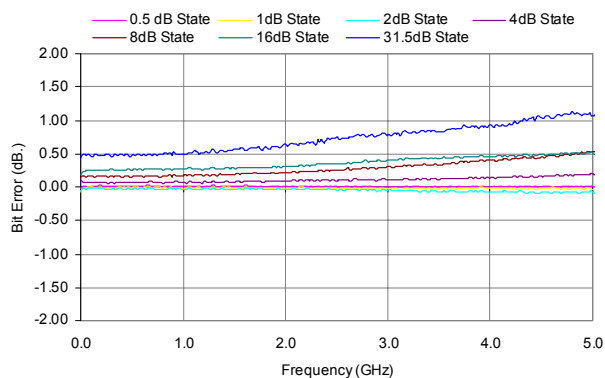


\*Monotonicity is held so long as Step-Error does not cross zero

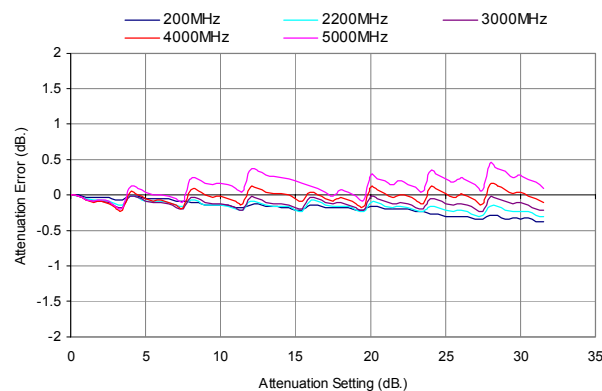
**Figure 4. 1dB Attenuation vs. Attenuation State**



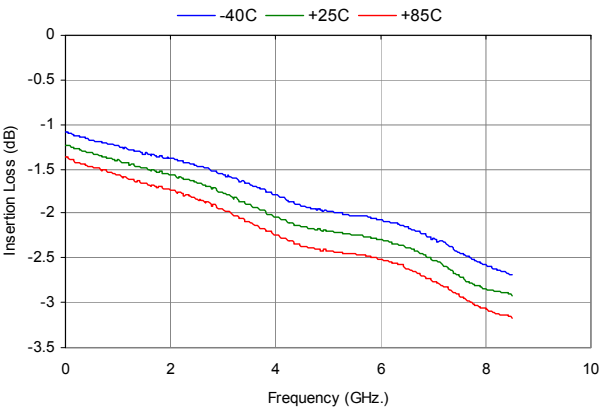
**Figure 5. 0.5dB Major State Bit Error**



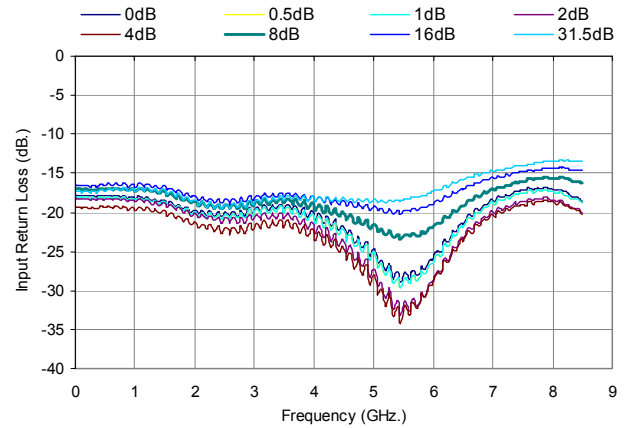
**Figure 6. 0.5dB Attenuation Error vs. Frequency**



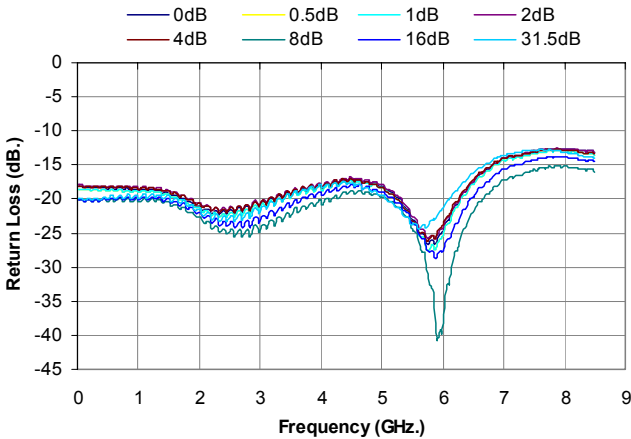
**Figure 7. Insertion Loss vs. Temperature**



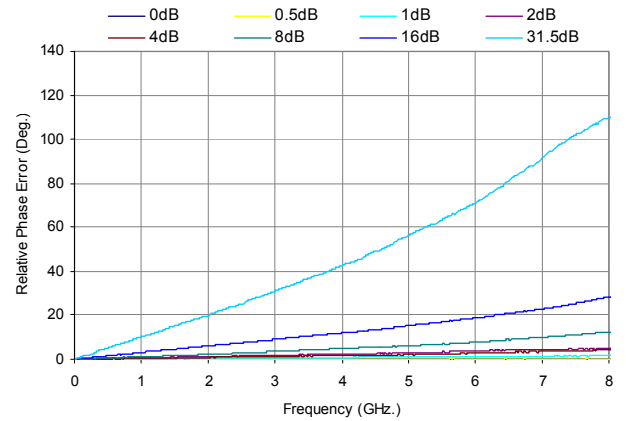
**Figure 8. Input Return Loss vs. Attenuation @ T = +25C**



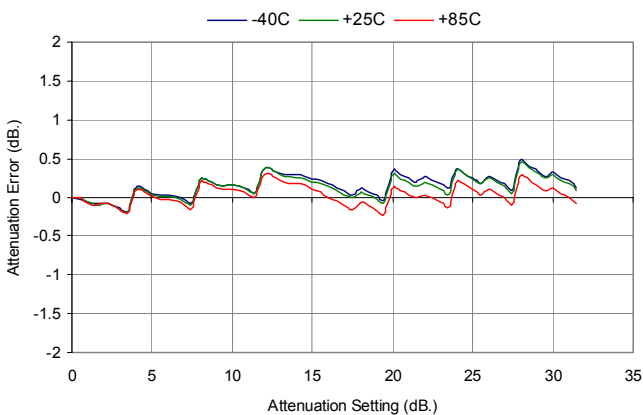
**Figure 9. Output Return Loss vs. Attenuation @ T = +25C**



**Figure 10. Relative Phase vs. Frequency**



**Figure 11. Attenuation Error vs. Temperature @ 5 GHz**



**Figure 12. Input IP3 vs. Frequency**

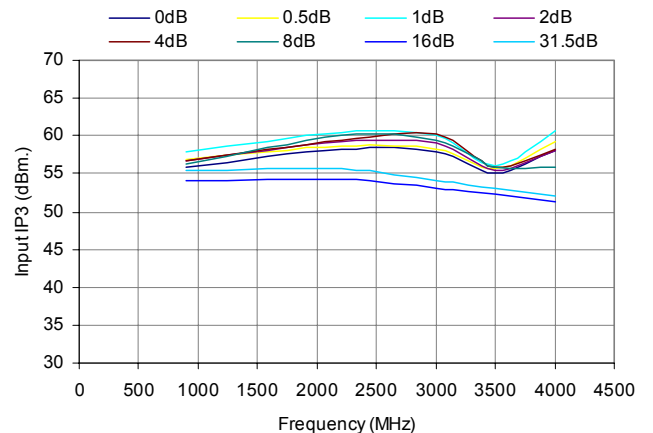


Figure 13. Pin Configuration (Top View)

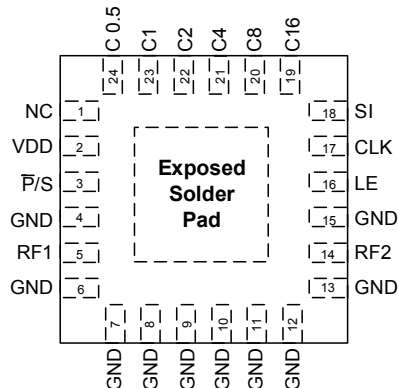


Table 2. Pin Descriptions

| Pin No. | Pin Name        | Description                     |
|---------|-----------------|---------------------------------|
| 1       | GND             | Ground                          |
| 2       | V <sub>DD</sub> | Power supply pin                |
| 3       | P/S             | Serial/Parallel mode select     |
| 4       | GND             | Ground                          |
| 5       | RF1             | RF1 port                        |
| 6 - 13  | GND             | Ground                          |
| 14      | RF2             | RF2 port                        |
| 15      | GND             | Ground                          |
| 16      | LE              | Latch Enable input              |
| 17      | CLK             | Serial interface clock input    |
| 18      | SI              | Serial Interface input          |
| 19      | C16             | Attenuation control bit, 16 dB  |
| 20      | C8              | Attenuation control bit, 8 dB   |
| 21      | C4              | Attenuation control bit, 4 dB   |
| 22      | C2              | Attenuation control bit, 2 dB   |
| 23      | C1              | Attenuation control bit, 1 dB   |
| 24      | C0.5            | Attenuation control bit, 0.5 dB |
| Paddle  | GND             | Ground for proper operation     |

### Exposed Solder Pad Connection

The exposed solder pad on the bottom of the package must be grounded for proper device operation.

### Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE43602 in the 24-lead 4x4 QFN package is MSL1.

### Switching Frequency

The PE43602 has a maximum 25 kHz switching rate. Switching rate is defined to be the speed at which the DSA can be toggled across attenuation states.

### Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS™ devices are immune to latch-up.

Table 3. Operating Ranges

| Parameter   | Min | Typ | Max            | Units      |
|---|-----|-----|----------------|------------|
| V <sub>DD</sub> Power Supply Voltage                                  | 3.0 | 3.3 |                | V          |
| V <sub>DD</sub> Power Supply Voltage                                  |     | 5.0 | 5.5            | V          |
| I <sub>DD</sub> Power Supply Current                                  |     | 70  | 350            | μA         |
| Digital Input High  | 2.6 |     | 5.5            | V          |
| P <sub>IN</sub> Input power (50Ω):<br>1 Hz ≤ 20 MHz<br>20 MHz ≤ 4 GHz |     |     | Fig. 14<br>+23 | dBm<br>dBm |
| T <sub>OP</sub> Operating temperature range                           | -40 | 25  | 85             | °C         |
| Digital Input Low   | 0   |     | 1              | V          |
| Digital Input Leakage <sup>1</sup>                                    |     |     | 15             | μA         |

Note 1. Input leakage current per Control pin

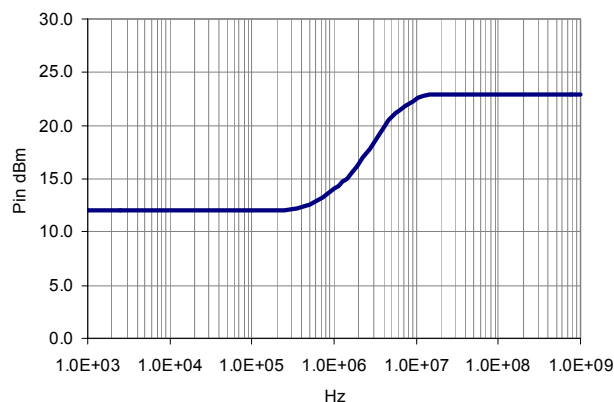
Table 4. Absolute Maximum Ratings

| Symbol           | Parameter/Conditions  | Min  | Max            | Units      |
|------------------|---|------|----------------|------------|
| V <sub>DD</sub>  | Power supply voltage  | -0.3 | 6.0            | V          |
| V <sub>I</sub>   | Voltage on any Digital input                                  | -0.3 | 5.8            | V          |
| T <sub>ST</sub>  | Storage temperature range                                     | -65  | 150            | °C         |
| P <sub>IN</sub>  | Input power (50Ω)<br>1 Hz ≤ 20 MHz<br>20 MHz ≤ 4 GHz          |      | Fig. 14<br>+23 | dBm<br>dBm |
| V <sub>ESD</sub> | ESD voltage (HBM) <sup>1</sup><br>ESD voltage (Machine Model) |      | 500<br>100     | V<br>V     |

Note: 1. Human Body Model (HBM, MIL\_STD 883 Method 3015.7)

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Figure 14. Maximum Power Handling Capability



### Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS™ device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

**Table 5. Control Voltage**

| State | Bias Condition                     |
|-------|------------------------------------|
| Low   | 0 to +1.0 Vdc at 2 $\mu$ A (typ)   |
| High  | +2.6 to +5 Vdc at 10 $\mu$ A (typ) |

**Table 6. Latch and Clock Specifications**

| Latch Enable | Shift Clock | Function  |
|--------------|-------------|---|
| X            | $\uparrow$  | Shift Register Clocked                                    |
| $\uparrow$   | X           | Contents of shift register transferred to attenuator core |

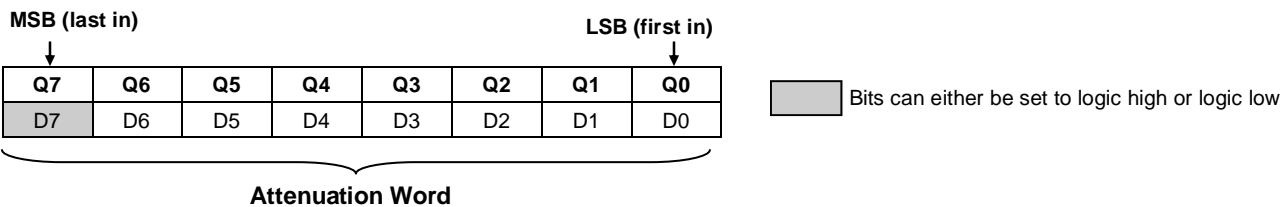
**Table 7. Parallel Truth Table**

| Parallel Control Setting |    |    |    |    |    | Attenuation Setting RF1-RF2 |
|--------------------------|----|----|----|----|----|-----------------------------|
| D6                       | D5 | D4 | D3 | D2 | D1 |                             |
| L                        | L  | L  | L  | L  | L  | Reference I.L.              |
| L                        | L  | L  | L  | L  | H  | 0.5 dB                      |
| L                        | L  | L  | L  | H  | L  | 1 dB                        |
| L                        | L  | L  | H  | L  | L  | 2 dB                        |
| L                        | L  | H  | L  | L  | L  | 4 dB                        |
| L                        | H  | L  | L  | L  | L  | 8 dB                        |
| H                        | L  | L  | L  | L  | L  | 16 dB                       |
| H                        | H  | H  | H  | H  | H  | 31.5 dB                     |

**Table 8. Serial Attenuation Word Truth Table**

| Attenuation Word |    |    |    |    |    |    |          | Attenuation Setting RF1-RF2 |
|------------------|----|----|----|----|----|----|----------|-----------------------------|
| D7               | D6 | D5 | D4 | D3 | D2 | D1 | D0 (LSB) |                             |
| X                | L  | L  | L  | L  | L  | L  | L        | Reference I.L.              |
| X                | L  | L  | L  | L  | L  | H  | L        | 0.5 dB                      |
| X                | L  | L  | L  | L  | H  | L  | L        | 1 dB                        |
| X                | L  | L  | L  | H  | L  | L  | L        | 2 dB                        |
| X                | L  | L  | H  | L  | L  | L  | L        | 4 dB                        |
| X                | L  | H  | L  | L  | L  | L  | L        | 8 dB                        |
| X                | H  | L  | L  | L  | L  | L  | L        | 16 dB                       |
| X                | H  | H  | H  | H  | H  | H  | L        | 31.5 dB                     |

**Table 9. Serial Register Map**



Attenuation Word is derived directly from the attenuation value. For example, to program the 12.5 dB state:

Attenuation Word: Multiply by 4 and convert to binary  $\rightarrow 4 * 12.5 \text{ dB} \rightarrow 50 \rightarrow \text{X0110010}$   
 Serial Input: X0110010

## Programming Options

### Parallel/Serial Selection

Either a parallel or serial interface can be used to control the PE43602. The  $\bar{P}/S$  bit provides this selection, with  $\bar{P}/S=LOW$  selecting the parallel interface and  $\bar{P}/S=HIGH$  selecting the serial interface.

### Parallel Mode Interface

The parallel interface consists of six CMOS-compatible control lines that select the desired attenuation state, as shown in *Table 7*.

The parallel interface timing requirements are defined by *Fig. 16* (Parallel Interface Timing Diagram), *Table 11* (Parallel Interface AC Characteristics), and switching speed (*Table 1*).

For *latched*-parallel programming the Latch Enable (LE) should be held LOW while changing attenuation state control values, then pulse LE HIGH to LOW (*per Fig. 16*) to latch new attenuation state into device.

For *direct* parallel programming, the Latch Enable (LE) line should be pulled HIGH. Changing attenuation state control values will change device state to new attenuation. Direct Mode is ideal for manual control of the device (using hardware, switches, or jumpers).

### Serial Interface

The serial interface is a 8-bit serial-in, parallel-out shift register buffered by a transparent latch. The 8-bits make up the Attenuation Word that controls the DSA. *Fig. 15* illustrates a example timing diagram for programming a state.

The serial-interface is controlled using three CMOS-compatible signals: Serial-In (SI), Clock (CLK), and Latch Enable (LE). The SI and CLK inputs allow data to be serially entered into the shift register. Serial data is clocked in LSB first.

The shift register must be loaded while LE is held LOW to prevent the attenuator value from changing as data is entered. The LE input should then be toggled HIGH and brought LOW again, latching the new data into the DSA. Attenuation Word truth table is listed in *Table 8*. A programming example of the serial register is illustrated in *Table 9*. The serial timing diagram is illustrated in *Fig. 15*.

### Power-up Control Settings

The PE43602 will always initialize to the maximum attenuation setting (31.5-dB) on power-up for both the serial and latched-parallel modes of operation and will remain in this setting until the user latches in the next programming word. In direct-parallel mode, the DSA can be preset to any state within the 31.5-dB range by pre-setting the parallel control pins prior to power-up. In this mode, there is a 400- $\mu$ s delay between the time the DSA is powered-up to the time the desired state is set. During this power-up delay, the device attenuates to the maximum attenuation setting (31.5-dB) before defaulting to the user defined state. If the control pins are left floating in this mode during power-up, the device will default to the minimum attenuation setting (insertion loss state).

Figure 15. Serial Timing Diagram

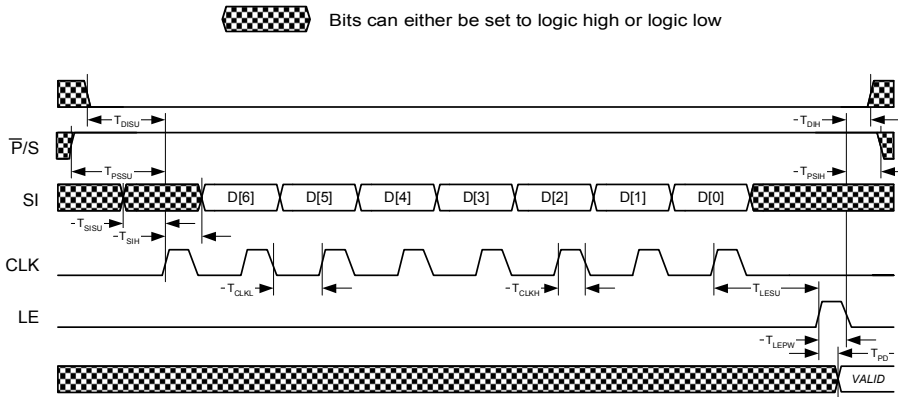


Figure 16. Latched-Parallel/Direct-Parallel Timing Diagram

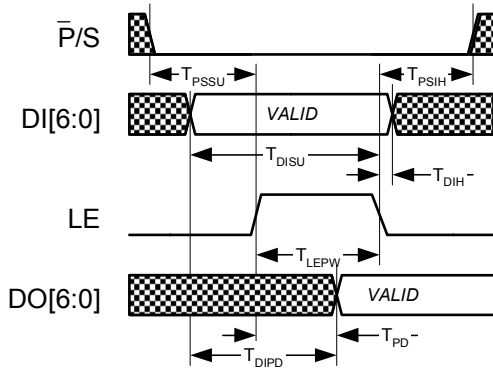


Table 10. Serial Interface AC Characteristics

$V_{DD} = 3.3$  or  $5.0$  V,  $-40^{\circ} C < T_A < 85^{\circ} C$ , unless otherwise specified

| Symbol     | Parameter  | Min. | Max. | Unit |
|------------|--|------|------|------|
| $f_{CLK}$  | Serial clock frequency   | -    | 10   | MHz  |
| $T_{CLKH}$ | Serial clock HIGH time   | 30   | -    | ns   |
| $T_{CLKL}$ | Serial clock LOW time  | 30   | -    | ns   |
| $T_{LESU}$ | Last serial clock rising edge setup time to Latch Enable rising edge | 10   | -    | ns   |
| $T_{LEPW}$ | Latch Enable minimum pulse width                                     | 30   | -    | ns   |
| $T_{SISU}$ | Serial data setup time   | 10   | -    | ns   |
| $T_{SIH}$  | Serial data hold time  | 10   | -    | ns   |
| $T_{DISU}$ | Parallel data setup time   | 100  | -    | ns   |
| $T_{DIH}$  | Parallel data hold time  | 100  | -    | ns   |
| $T_{ASU}$  | Address setup time   | 100  | -    | ns   |
| $T_{AH}$   | Address hold time  | 100  | -    | ns   |
| $T_{PSSU}$ | Parallel/Serial setup time   | 100  | -    | ns   |
| $T_{PSH}$  | Parallel/Serial hold time  | 100  | -    | ns   |
| $T_{PD}$   | Digital register delay (internal)                                    | -    | 10   | ns   |

Note:  $f_{CLK}$  is verified during the functional pattern test. Serial programming sections of the functional pattern are clocked at 10 MHz to verify  $f_{CLK}$  specification.

Table 11. Parallel and Direct Interface AC Characteristics

$V_{DD} = 3.3$  or  $5.0$  V,  $-40^{\circ} C < T_A < 85^{\circ} C$ , unless otherwise specified

| Symbol     | Parameter   | Min | Max | Unit |
|------------|---|-----|-----|------|
| $T_{LEPW}$ | Latch Enable minimum pulse width                    | 30  | -   | ns   |
| $T_{DISU}$ | Parallel data setup time                            | 100 | -   | ns   |
| $T_{DIH}$  | Parallel data hold time                             | 100 | -   | ns   |
| $T_{PSSU}$ | Parallel/Serial setup time                          | 100 | -   | ns   |
| $T_{PSIH}$ | Parallel/Serial hold time                           | 100 | -   | ns   |
| $T_{PD}$   | Digital register delay (internal)                   | -   | 10  | ns   |
| $T_{DIPD}$ | Digital register delay (internal, direct mode only) | -   | 5   | ns   |

## Evaluation Kit

The Digital Attenuator Evaluation Kit board was designed to ease customer evaluation of the PE43602 Digital Step Attenuator.

### *Direct-Parallel Programming Procedure*

For automated direct-parallel programming, connect the test harness provided with the EVK from the parallel port of the PC to the J1 & Serial header pin and set the D0-D6 SP3T switches to the 'MIDDLE' toggle position. Position the Parallel/Serial (P/S) select switch to the Parallel (or left) position. The evaluation software is written to operate the DSA in either Parallel or Serial-Addressable Mode. Ensure that the software is set to program in *Direct-Parallel* mode. Using the software, enable or disable each setting to the desired attenuation state. The software automatically programs the DSA each time an attenuation state is enabled or disabled.

For manual direct-parallel programming, disconnect the test harness provided with the EVK from the J1 and Serial header pins. Position the Parallel/Serial (P/S) select switch to the Parallel (or left) position. The LE pin on the Serial header must be tied to  $V_{DD}$ . Switches D0-D6 are SP3T switches which enable the user to manually program the parallel bits. When any input D0-D6 is toggled 'UP', logic high is presented to the parallel input. When toggled 'DOWN', logic low is presented to the parallel input. Setting D0-D6 to the 'MIDDLE' toggle position presents an OPEN, which forces an on-chip logic low. *Table 9* depicts the parallel programming truth table and *Fig. 16* illustrates the parallel programming timing diagram.

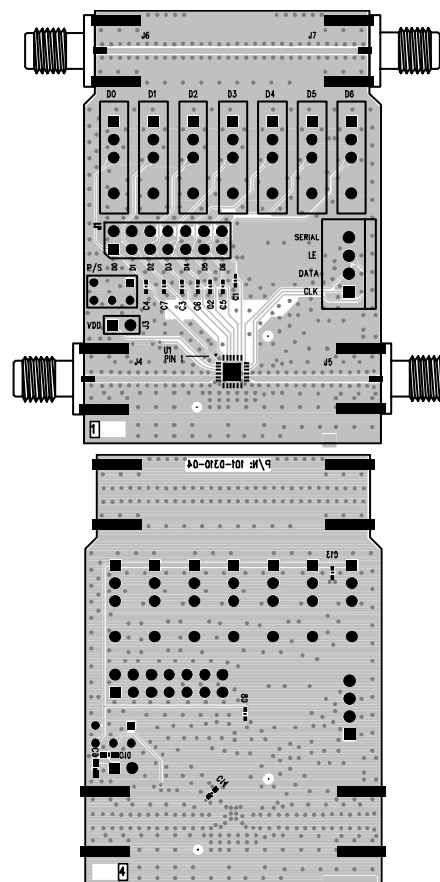
### *Latched-Parallel Programming Procedure*

For automated latched-parallel programming, the procedure is identical to the direct-parallel method. The user only must ensure that *Latched-Parallel* is selected in the software.

For manual latched-parallel programming, the procedure is identical to direct-parallel except now the LE pin on the Serial header must be logic low

**Figure 17. Evaluation Board Layout**

Peregrine Specification 101-0310



Note: Reference Figure 18 for Evaluation Board Schematic

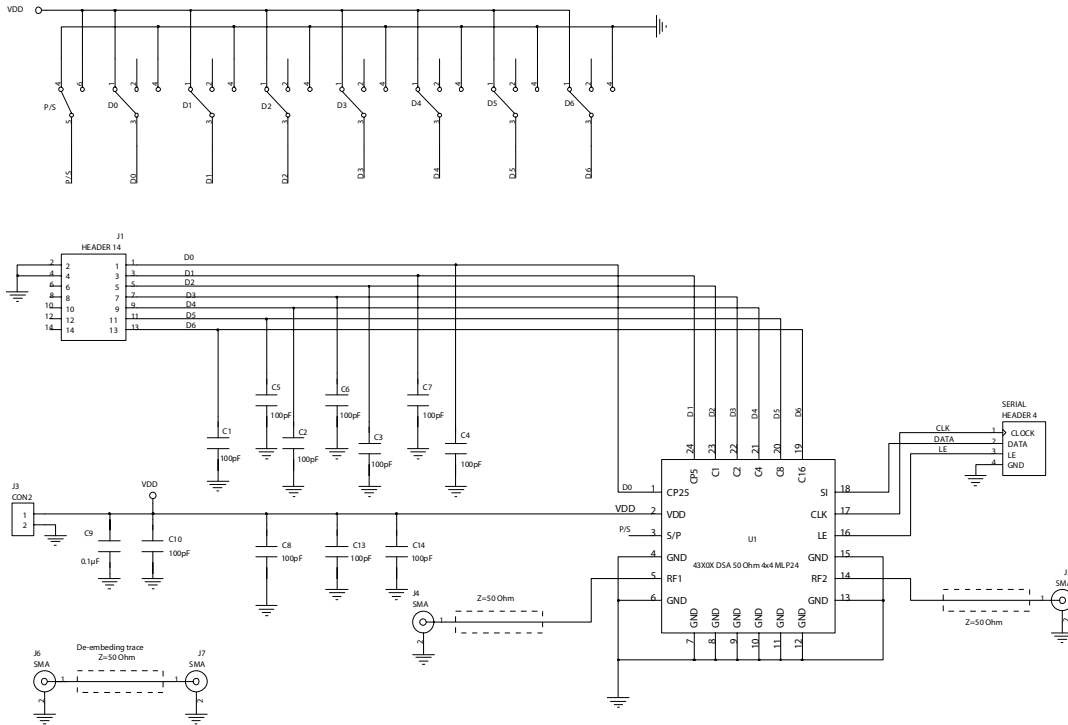
as the parallel bits are applied. The user must then pulse LE from 0V to  $V_{DD}$  and back to 0V to latch the programming word into the DSA. LE must be logic low prior to programming the next word.

### *Serial Programming Procedure*

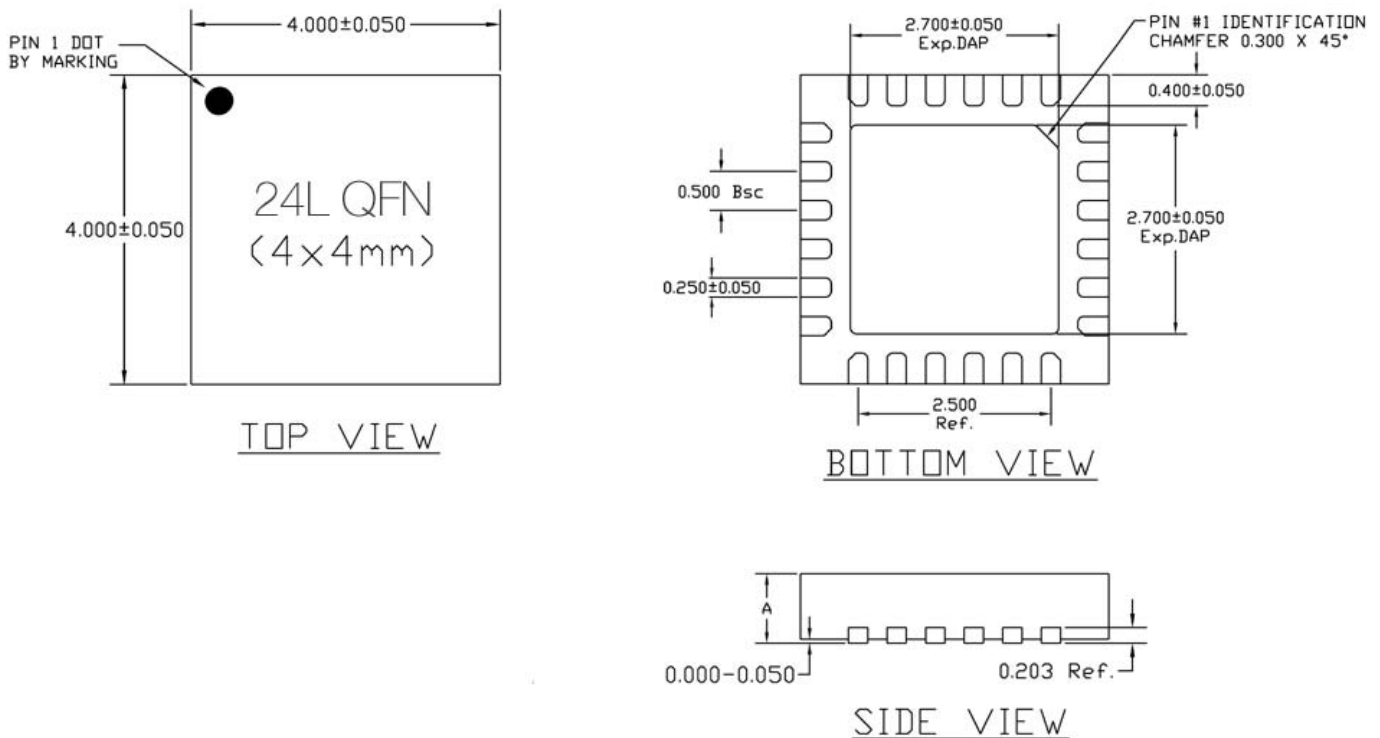
Position the Parallel/Serial (P/S) select switch to the Serial (or right) position. The evaluation software is written to operate the DSA in either Parallel or Serial Mode. Ensure that the software is set to program in Serial mode. Using the software, enable or disable each setting to the desired attenuation state. The software automatically programs the DSA each time an attenuation state is enabled or disabled.



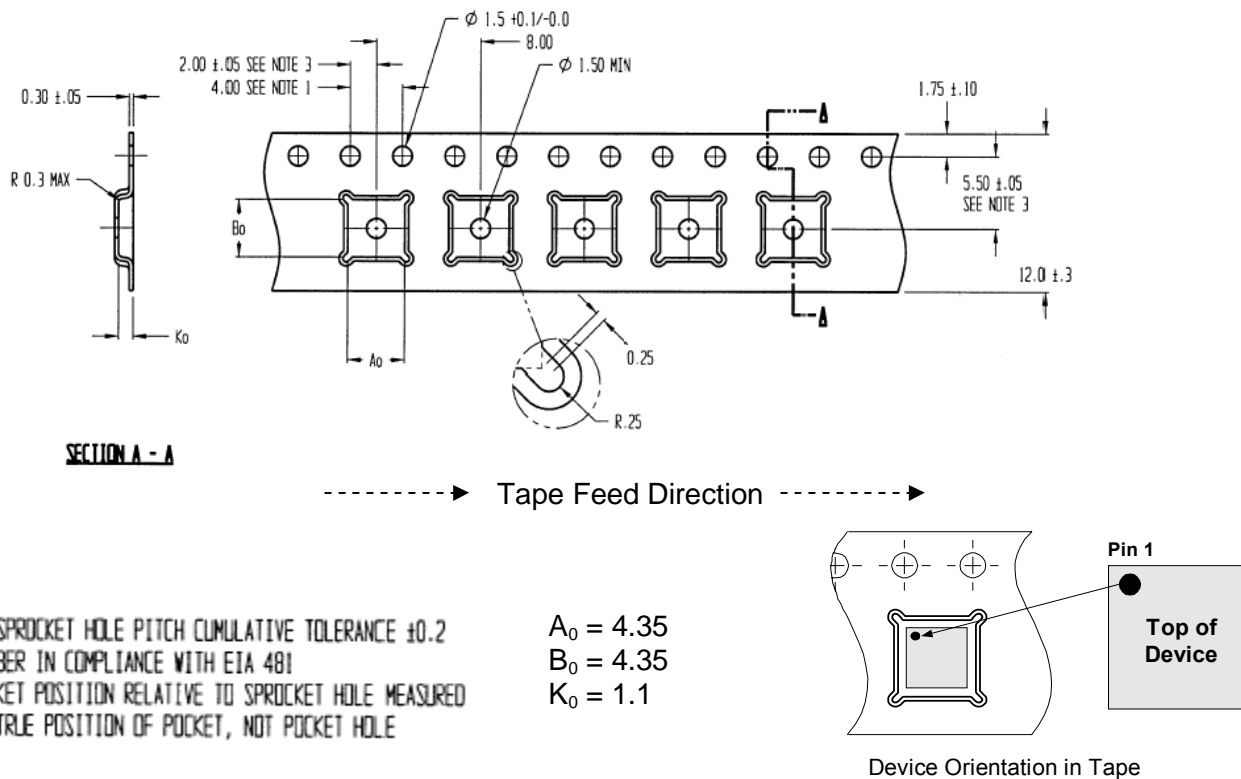
**Figure 18. Evaluation Board Schematic**  
Peregrine Specification 102-0379



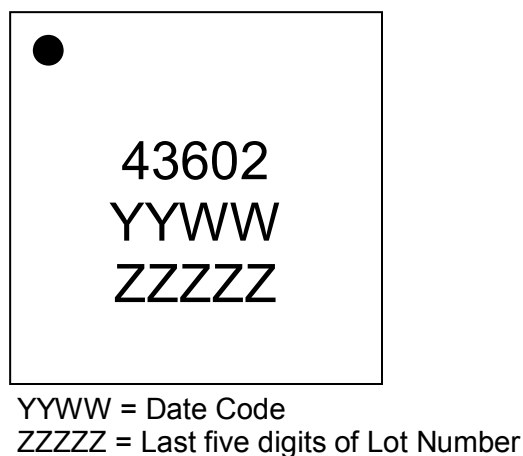
**Figure 19. Package Drawing**



**Figure 20. Tape and Reel Drawing**



**Figure 21. Marking Specifications**



**Table 12. Ordering Information**

| Order Code    | Part Marking | Description                | Package                 | Shipping Method            |
|---------------|--------------|----------------------------|-------------------------|----------------------------|
| PE43602 MLI   | 43602        | PE43602G-24QFN 4x4mm-75A   | Green 24-lead 4x4mm QFN | Bulk or tape cut from reel |
| PE43602 MLI-Z | 43602        | PE43602G-24QFN 4x4mm-3000C | Green 24-lead 4x4mm QFN | 3000 units / T&R           |
| EK43602-01    | PE43602 -EK  | PE43602-24QFN 4x4mm-EK     | Evaluation Kit          | 1 / Box                    |

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## Data Sheet Identification

### **Advance Information**

The product is in a formative or design stage. The data sheet contains design target specifications for product development. Specifications and features may change in any manner without notice.

### **Preliminary Specification**

The data sheet contains preliminary data. Additional data may be added at a later date. Peregrine reserves the right to change specifications at any time without notice in order to supply the best possible product.

### **Product Specification**

The data sheet contains final data. In the event Peregrine decides to change the specifications, Peregrine will notify customers of the intended changes by issuing a DCN (Document Change Notice).

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